Universal clock generators simplify traditional board designs by synthesizing frequencies from either a reference input clock or a common low-cost crystal, providing low-jitter output clocks. When used together with Microsemi clock distribution fanout buffers, the clock generators provide customers with improved board performance and complete timing solutions.

Any-Rate Clock Synthesis Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Low- Jitter APLLs	Typical Jitter fs RMS	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
ZL30236	2	1 XTAL	20 M, 24.576 M			2	700			8	4	1 k–750 M	OTP	SPI/I2C	3.3 + 1.8	11 × 11
ZL30237	2	1 XTAL	20 M, 24.576 M			2	700	٠	0.24	8	4	1 k–750 M	OTP	SPI/I2C	3.3 + 1.8	11 × 11
ZL30230	4	1 XTAL	20 M, 24.576 M			2	700			4–12	4–12	1 k–750 M	OTP	SPI/I2C	3.3 + 1.8	11 × 11
MAX24405	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	1801			0–5	0–10	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24505	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180 ¹			0–5	0–10	<1 Hz–750 M	Int EE	SPI	3.3 + 1.8	10 × 10
MAX24410	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180¹			0–10	0–20	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24510	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180¹			0–10	0–20	<1 Hz–750 M	Int EE	SPI	3.3 + 1.8	10 × 10
ZL30250	1	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	160 ¹	٠	0.01	0–3	0–6	<1 Hz-1035 M ²	Ext EE3	SPI/I2C	3.3 + 1.8	5 × 5
ZL30251	1	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	160 ¹	٠	0.01	0–3	0–6	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30244	2	2 XTAL/SE, 6 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	2	160¹	٠	0.01	0–6	0–12	<1 Hz-1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 × 10
ZL30245	2	2 XTAL/SE, 6 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	2	160 ¹	٠	0.01	0–6	0–12	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 10
ZL30260	2	1 XTAL/SE, 3D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	170 ¹	٠	0.01	0–6	0–12	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30261	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	170 ¹	٠	0.01	0–6	0–12	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30262	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	170 ¹	٠	0.01	0–10	0–20	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30263	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	1	170 ¹	٠	0.01	0–10	0–20	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30264	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	2	170 ¹	٠	0.01	0–6	0–12	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note⁵	8 × 8
ZL30265	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M-1250 M	2	170 ¹	٠	0.01	0–6	0–12	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30266	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	170 ¹	•	0.01	0–10	0–20	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30267	4	1 XTALI/SE, 3 D/SE	25 M-60 M	9.72 M–300 M	9.72 M-1250 M	2	170 ¹	٠	0.01	0–10	0–20	1 Hz-1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8

Abbreviation Key:

D = differential Int EE = internal EEPROM SE = single-ended (CMOS) OTP = one-time programmable NCO = numerically controlled oscillator 1 = integer-mode APLL-only operation Ext EE = external EEPROM 2 = spread spectrum-capable

3 = up to four configurations (pin-selectable)

4 = up to eight configurations (pin-selectable)

5 = 2.5 V only, 3.3 V only, 1.8 V + 2.5 V, 1.8 V + 3.3 V



Rate Conversion/Jitter Attenuation Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Jitter	Typical Jitter fs RMS	DPLL Features: Ref. Switching/ Holdover/ DPLL Bandwidth	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
MAX24605	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180 ¹	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–5	0–10	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24610	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180¹	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–10	0–20	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
ZL30159	1	1 XTAL, 1 D	20 M or 24.578 M	1 Hz–177.5 M	1 Hz–750 M	1	<1000				0	2	1 Hz–177.5 M		SPI/I2C	3.3 + 1.8	9×9
ZL30252	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz-300 M	1 kHz–1250 M	1	160 ¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz-1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5×5
ZL30253	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz-300 M	1 kHz–1250 M	1	160 ¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30254	1	1 XTAL, 2 SE	49.152 MHz	8 kHz or 25 MHz		1	<1 ps	Glitchless/ Digital Hold/ 25 Hz			2	0	125 MHz or 156.25 MHz		None	3.3 + 1.8	5 × 5
ZL30255	2	2 XTAL/SE, 6 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	2	160¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–6	0–12	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 10

Abbreviation Key:

D = differential Ext EE = external EEPROM 1 = integer-mode APLL-only operation SE = single-ended (CMOS) Int EE = internal EEPROM 2 = spread spectrum-capable NCO = numerically controlled oscillator OTP = one-time programmable 3 = up to four configurations pin-selectable



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